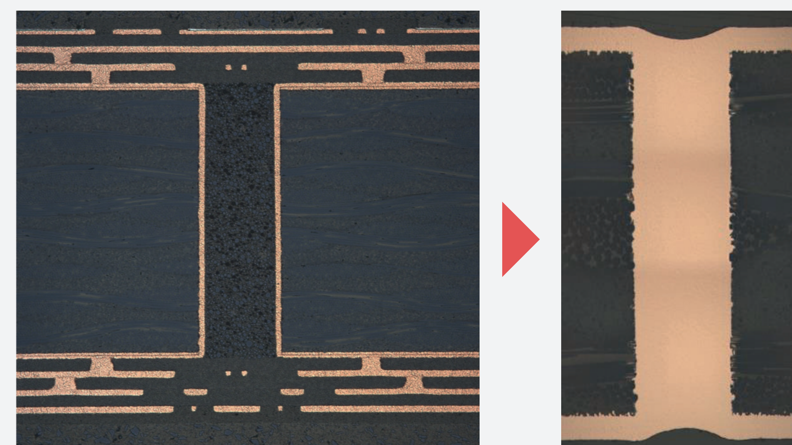
Inpulse® 2THF2

mks Atotech

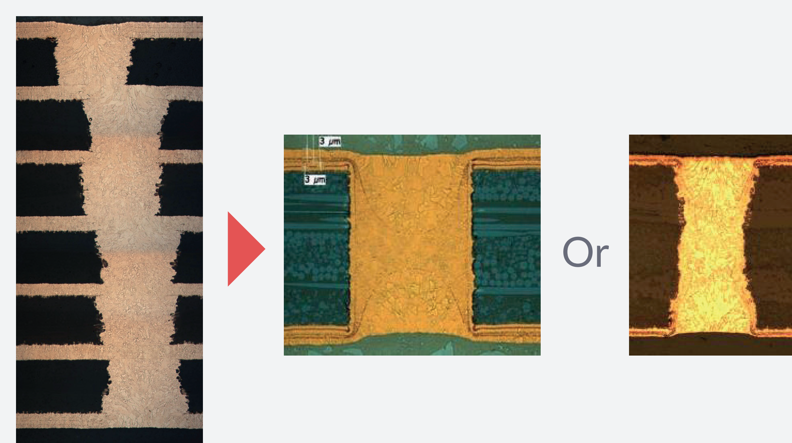
Through via filling for IC/CSP substrate

Further possible applications for Inpulse® 2THF2

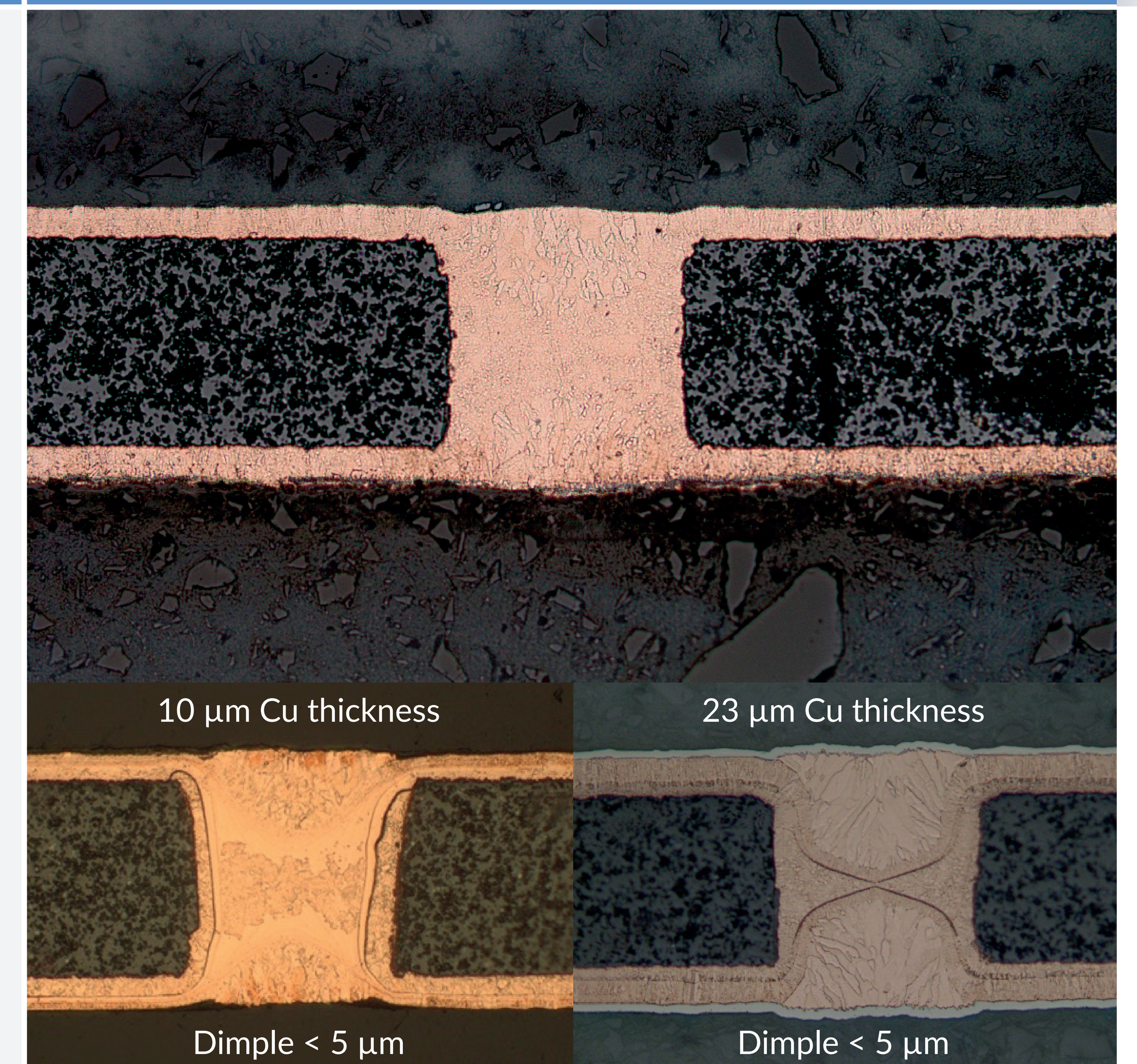
Replacement of plugging process



Replacement of stacking process



THF: Only 10 µm copper on surface including copper foil



Dramatically reduced costs compared to conventional plugging technology

Economic and reliable through hole filling (THF)

The Inpulse® 2THF2 electrolyte together with the unique Uniplate® InPulse 2 system is ideally suited for through hole filling especially for core material with copper foil thickness less than 5 µm. The process provides excellent surface uniformity with minimum surface plated copper. Inpulse® 2THF2 enables the option to run through hole metallization and electrolytic copper THF in one conveyorized process line.

Features and benefits

- Patented bridge plating technology enables inclusion free copper filling of through holes
- Full panel plating for best possible plated copper surface distribution
- Capable for core material of 50 µm up to 300 µm with copper foil ≤ 5 µm thickness
- Improved reliability, CTE mismatch eliminated
- Deposit plated with the Inpulse® 2THF2 system meets all current reliability standards
- Economical process savings in: copper metal, soldermask, etching process and processing time